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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	416
Number of Logic Elements/Cells	4160
Total RAM Bits	53248
Number of I/O	246
Number of Gates	263000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	324-BGA
Supplier Device Package	324-FBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k100efc324-3

Email: info@E-XFL.COM

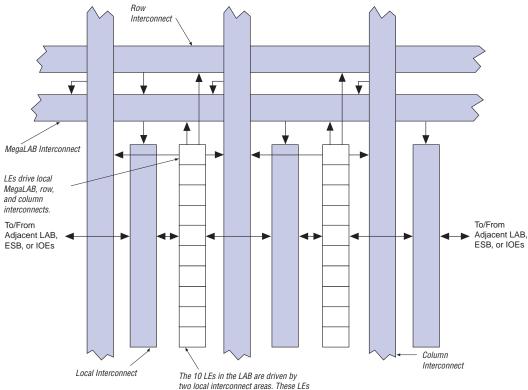
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Logic Array Block

Each LAB consists of 10 LEs, the LEs' associated carry and cascade chains, LAB control signals, and the local interconnect. The local interconnect transfers signals between LEs in the same or adjacent LABs, IOEs, or ESBs. The Quartus II Compiler places associated logic within an LAB or adjacent LABs, allowing the use of a fast local interconnect for high performance. Figure 3 shows the APEX 20K LAB.

APEX 20K devices use an interleaved LAB structure. This structure allows each LE to drive two local interconnect areas. This feature minimizes use of the MegaLAB and FastTrack interconnect, providing higher performance and flexibility. Each LE can drive 29 other LEs through the fast local interconnect.





Altera Corporation 11

can drive two local interconnect areas.

Cascade Chain

With the cascade chain, the APEX 20K architecture can implement functions with a very wide fan-in. Adjacent LUTs can compute portions of a function in parallel; the cascade chain serially connects the intermediate values. The cascade chain can use a logical AND or logical OR (via De Morgan's inversion) to connect the outputs of adjacent LEs. Each additional LE provides four more inputs to the effective width of a function, with a short cascade delay. Cascade chain logic can be created automatically by the Quartus II software Compiler during design processing, or manually by the designer during design entry.

Cascade chains longer than ten LEs are implemented automatically by linking LABs together. For enhanced fitting, a long cascade chain skips alternate LABs in a MegaLAB structure. A cascade chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure. Figure 7 shows how the cascade function can connect adjacent LEs to form functions with a wide fan-in.

Figure 7. APEX 20K Cascade Chain

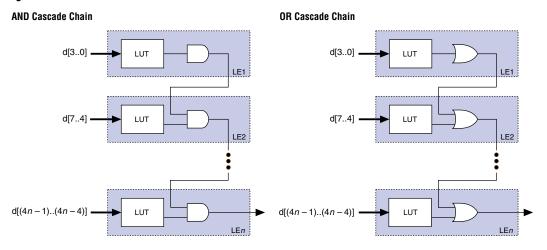
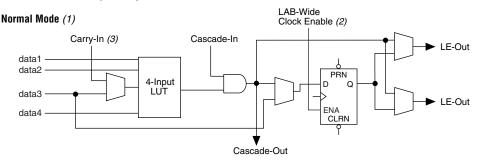
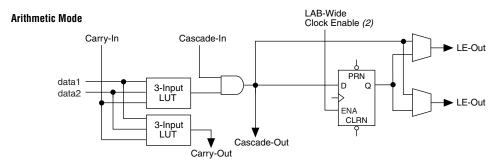
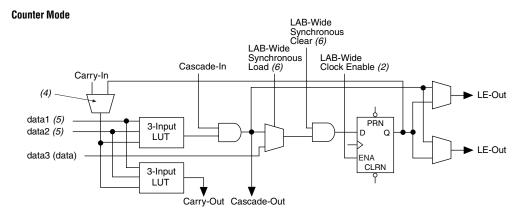


Figure 8. APEX 20K LE Operating Modes







Notes to Figure 8:

- (1) LEs in normal mode support register packing.
- (2) There are two LAB-wide clock enables per LAB.
- (3) When using the carry-in in normal mode, the packed register feature is unavailable.
- (4) A register feedback multiplexer is available on LE1 of each LAB.
- (5) The DATA1 and DATA2 input signals can supply counter enable, up or down control, or register feedback signals for LEs other than the second LE in an LAB.
- (6) The LAB-wide synchronous clear and LAB wide synchronous load affect all registers in an LAB.

The counter mode uses two three-input LUTs: one generates the counter data, and the other generates the fast carry bit. A 2-to-1 multiplexer provides synchronous loading, and another AND gate provides synchronous clearing. If the cascade function is used by an LE in counter mode, the synchronous clear or load overrides any signal carried on the cascade chain. The synchronous clear overrides the synchronous load. LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output.

Clear & Preset Logic Control

Logic for the register's clear and preset signals is controlled by LAB-wide signals. The LE directly supports an asynchronous clear function. The Quartus II software Compiler can use a NoT-gate push-back technique to emulate an asynchronous preset. Moreover, the Quartus II software Compiler can use a programmable NoT-gate push-back technique to emulate simultaneous preset and clear or asynchronous load. However, this technique uses three additional LEs per register. All emulation is performed automatically when the design is compiled. Registers that emulate simultaneous preset and load will enter an unknown state upon power-up or when the chip-wide reset is asserted.

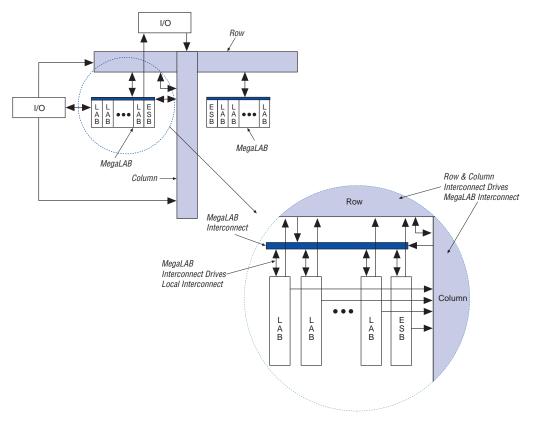
In addition to the two clear and preset modes, APEX 20K devices provide a chip-wide reset pin (DEV_CLRn) that resets all registers in the device. Use of this pin is controlled through an option in the Quartus II software that is set before compilation. The chip-wide reset overrides all other control signals. Registers using an asynchronous preset are preset when the chip-wide reset is asserted; this effect results from the inversion technique used to implement the asynchronous preset.

FastTrack Interconnect

In the APEX 20K architecture, connections between LEs, ESBs, and I/O pins are provided by the FastTrack Interconnect. The FastTrack Interconnect is a series of continuous horizontal and vertical routing channels that traverse the device. This global routing structure provides predictable performance, even in complex designs. In contrast, the segmented routing in FPGAs requires switch matrices to connect a variable number of routing paths, increasing the delays between logic resources and reducing performance.

The FastTrack Interconnect consists of row and column interconnect channels that span the entire device. The row interconnect routes signals throughout a row of MegaLAB structures; the column interconnect routes signals throughout a column of MegaLAB structures. When using the row and column interconnect, an LE, IOE, or ESB can drive any other LE, IOE, or ESB in a device. See Figure 9.

Figure 10. FastTrack Connection to Local Interconnect



Source	Destination								
	Row I/O Pin	Column I/O Pin	LE	ESB	Local Interconnect	MegaLAB Interconnect	Row FastTrack Interconnect	Column FastTrack Interconnect	FastRow Interconnect
Row I/O Pin					✓	✓	✓	✓	
Column I/O Pin								✓	√ (1)
LE					✓	✓	✓	✓	
ESB					✓	✓	✓	✓	
Local Interconnect	✓	✓	✓	✓					
MegaLAB Interconnect					✓				
Row FastTrack Interconnect						✓		✓	
Column						✓	✓		
FastTrack Interconnect									
FastRow Interconnect					✓ (1)				

Note to Table 9:

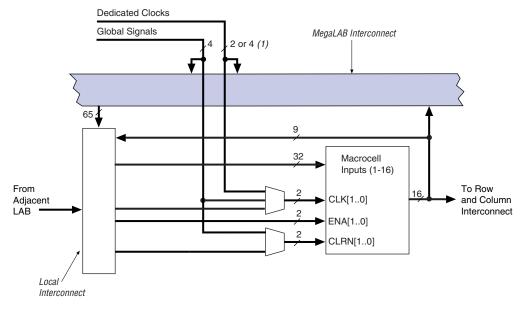
(1) This connection is supported in APEX 20KE devices only.

Product-Term Logic

The product-term portion of the MultiCore architecture is implemented with the ESB. The ESB can be configured to act as a block of macrocells on an ESB-by-ESB basis. Each ESB is fed by 32 inputs from the adjacent local interconnect; therefore, it can be driven by the MegaLAB interconnect or the adjacent LAB. Also, nine ESB macrocells feed back into the ESB through the local interconnect for higher performance. Dedicated clock pins, global signals, and additional inputs from the local interconnect drive the ESB control signals.

In product-term mode, each ESB contains 16 macrocells. Each macrocell consists of two product terms and a programmable register. Figure 13 shows the ESB in product-term mode.

Figure 13. Product-Term Logic in ESB



Note to Figure 13:

(1) APEX 20KE devices have four dedicated clocks.

Macrocells

APEX 20K macrocells can be configured individually for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register.

Combinatorial logic is implemented in the product terms. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as parallel expanders to be used to increase the logic available to another macrocell. One product term can be inverted; the Quartus II software uses this feature to perform DeMorgan's inversion for more efficient implementation of wide OR functions. The Quartus II software Compiler can use a NOT-gate push-back technique to emulate an asynchronous preset. Figure 14 shows the APEX 20K macrocell.

From Previous Macrocell Product-Macrocell Term Product-Select Term Logic Matrix Parallel Expander Switch Product-Macrocell Term Product-Select Term Logic Matrix Parallel Expander Switch 32 Signals from To Next

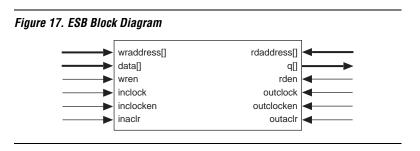
Figure 16. APEX 20K Parallel Expanders

Embedded System Block

Local Interconnect

The ESB can implement various types of memory blocks, including dual-port RAM, ROM, FIFO, and CAM blocks. The ESB includes input and output registers; the input registers synchronize writes, and the output registers can pipeline designs to improve system performance. The ESB offers a dual-port mode, which supports simultaneous reads and writes at two different clock frequencies. Figure 17 shows the ESB block diagram.

Macrocell



Input/Output Clock Mode

The input/output clock mode contains two clocks. One clock controls all registers for inputs into the ESB: data input, WE, RE, read address, and write address. The other clock controls the ESB data output registers. The ESB also supports clock enable and asynchronous clear signals; these signals also control the reading and writing of registers independently. Input/output clock mode is commonly used for applications where the reads and writes occur at the same system frequency, but require different clock enable signals for the input and output registers. Figure 21 shows the ESB in input/output clock mode.

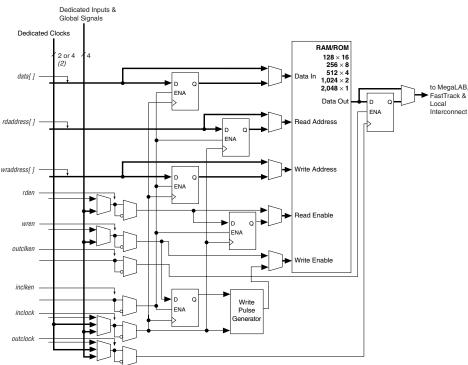


Figure 21. ESB in Input/Output Clock Mode Note (1)

Notes to Figure 21:

- (1) All registers can be cleared asynchronously by ESB local interconnect signals, global signals, or the chip-wide reset.
- (2) APEX 20KE devices have four dedicated clocks.

Single-Port Mode

The APEX 20K ESB also supports a single-port mode, which is used when simultaneous reads and writes are not required. See Figure 22.

Implementing Logic in ROM

In addition to implementing logic with product terms, the ESB can implement logic functions when it is programmed with a read-only pattern during configuration, creating a large LUT. With LUTs, combinatorial functions are implemented by looking up the results, rather than by computing them. This implementation of combinatorial functions can be faster than using algorithms implemented in general logic, a performance advantage that is further enhanced by the fast access times of ESBs. The large capacity of ESBs enables designers to implement complex functions in one logic level without the routing delays associated with linked LEs or distributed RAM blocks. Parameterized functions such as LPM functions can take advantage of the ESB automatically. Further, the Quartus II software can implement portions of a design with ESBs where appropriate.

Programmable Speed/Power Control

APEX 20K ESBs offer a high-speed mode that supports very fast operation on an ESB-by-ESB basis. When high speed is not required, this feature can be turned off to reduce the ESB's power dissipation by up to 50%. ESBs that run at low power incur a nominal timing delay adder. This Turbo BitTM option is available for ESBs that implement product-term logic or memory functions. An ESB that is not used will be powered down so that it does not consume DC current.

Designers can program each ESB in the APEX 20K device for either high-speed or low-power operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths operate at reduced power.

I/O Structure

The APEX 20K IOE contains a bidirectional I/O buffer and a register that can be used either as an input register for external data requiring fast setup times, or as an output register for data requiring fast clock-to-output performance. IOEs can be used as input, output, or bidirectional pins. For fast bidirectional I/O timing, LE registers using local routing can improve setup times and OE timing. The Quartus II software Compiler uses the programmable inversion option to invert signals from the row and column interconnect automatically where appropriate. Because the APEX 20K IOE offers one output enable per pin, the Quartus II software Compiler can emulate open-drain operation efficiently.

The APEX 20K IOE includes programmable delays that can be activated to ensure zero hold times, minimum clock-to-output times, input IOE register-to-core register transfers, or core-to-output IOE register transfers. A path in which a pin directly drives a register may require the delay to ensure zero hold time, whereas a path in which a pin drives a register through combinatorial logic may not require the delay.

Each IOE drives a row, column, MegaLAB, or local interconnect when used as an input or bidirectional pin. A row IOE can drive a local, MegaLAB, row, and column interconnect; a column IOE can drive the column interconnect. Figure 27 shows how a row IOE connects to the interconnect.

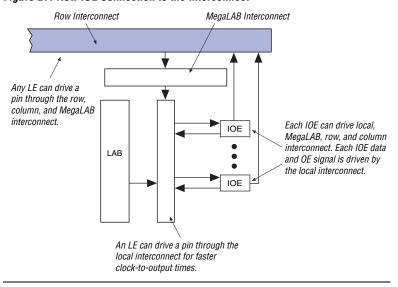


Figure 27. Row IOE Connection to the Interconnect

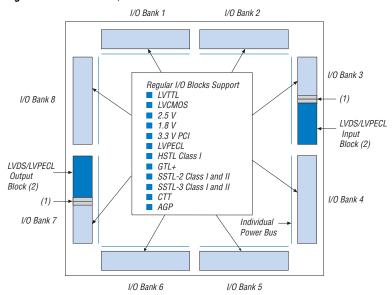


Figure 29. APEX 20KE I/O Banks

Notes to Figure 29:

- For more information on placing I/O pins in LVDS blocks, refer to the Guidelines for Using LVDS Blocks section in Application Note 120 (Using LVDS in APEX 20KE Devices).
- (2) If the LVDS input and output blocks are not used for LVDS, they can support all of the I/O standards and can be used as input, output, or bidirectional pins with V_{CCIO} set to 3.3 V, 2.5 V, or 1.8 V.

Power Sequencing & Hot Socketing

Because APEX 20K and APEX 20KE devices can be used in a mixed-voltage environment, they have been designed specifically to tolerate any possible power-up sequence. Therefore, the $V_{\rm CCIO}$ and $V_{\rm CCINT}$ power supplies may be powered in any order.



For more information, please refer to the "Power Sequencing Considerations" section in the *Configuring APEX 20KE & APEX 20KC Devices* chapter of the *Configuration Devices Handbook*.

Signals can be driven into APEX 20K devices before and during power-up without damaging the device. In addition, APEX 20K devices do not drive out during power-up. Once operating conditions are reached and the device is configured, APEX 20K and APEX 20KE devices operate as specified by the user.

Clock Phase & Delay Adjustment

The APEX 20KE ClockShift feature allows the clock phase and delay to be adjusted. The clock phase can be adjusted by 90° steps. The clock delay can be adjusted to increase or decrease the clock delay by an arbitrary amount, up to one clock period.

LVDS Support

Two PLLs are designed to support the LVDS interface. When using LVDS, the I/O clock runs at a slower rate than the data transfer rate. Thus, PLLs are used to multiply the I/O clock internally to capture the LVDS data. For example, an I/O clock may run at 105 MHz to support 840 megabits per second (Mbps) LVDS data transfer. In this example, the PLL multiplies the incoming clock by eight to support the high-speed data transfer. You can use PLLs in EP20K400E and larger devices for high-speed LVDS interfacing.

Lock Signals

The APEX 20KE ClockLock circuitry supports individual LOCK signals. The LOCK signal drives high when the ClockLock circuit has locked onto the input clock. The LOCK signals are optional for each ClockLock circuit; when not used, they are I/O pins.

ClockLock & ClockBoost Timing Parameters

For the ClockLock and ClockBoost circuitry to function properly, the incoming clock must meet certain requirements. If these specifications are not met, the circuitry may not lock onto the incoming clock, which generates an erroneous clock within the device. The clock generated by the ClockLock and ClockBoost circuitry must also meet certain specifications. If the incoming clock meets these requirements during configuration, the APEX 20K ClockLock and ClockBoost circuitry will lock onto the clock during configuration. The circuit will be ready for use immediately after configuration. In APEX 20KE devices, the clock input standard is programmable, so the PLL cannot respond to the clock until the device is configured. The PLL locks onto the input clock as soon as configuration is complete. Figure 30 shows the incoming and generated clock specifications.



For more information on ClockLock and ClockBoost circuitry, see *Application Note 115: Using the ClockLock and ClockBoost PLL Features in APEX Devices*.

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

All APEX 20K devices provide JTAG BST circuitry that complies with the IEEE Std. 1149.1-1990 specification. JTAG boundary-scan testing can be performed before or after configuration, but not during configuration. APEX 20K devices can also use the JTAG port for configuration with the Quartus II software or with hardware using either Jam Files (.jam) or Jam Byte-Code Files (.jbc). Finally, APEX 20K devices use the JTAG port to monitor the logic operation of the device with the SignalTap embedded logic analyzer. APEX 20K devices support the JTAG instructions shown in Table 19. Although EP20K1500E devices support the JTAG BYPASS and SignalTap instructions, they do not support boundary-scan testing or the use of the JTAG port for configuration.

Table 19. APEX 20K JT	TAG Instructions
JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern to be output at the device pins. Also used by the SignalTap embedded logic analyzer.
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS (1)	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through selected devices to adjacent devices during normal device operation.
USERCODE	Selects the 32-bit USERCODE register and places it between the TDI and TDO pins, allowing the USERCODE to be serially shifted out of TDO.
IDCODE	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
ICR Instructions	Used when configuring an APEX 20K device via the JTAG port with a MasterBlaster [™] or ByteBlasterMV [™] download cable, or when using a Jam File or Jam Byte-Code File via an embedded processor.
SignalTap Instructions (1)	Monitors internal device operation with the SignalTap embedded logic analyzer.

Note to Table 19:

(1) The EP20K1500E device supports the JTAG BYPASS instruction and the SignalTap instructions.

Table 22 shows the JTAG timing parameters and values for APEX 20K devices

Table 2	Table 22. APEX 20K JTAG Timing Parameters & Values						
Symbol	Parameter	Min	Max	Unit			
t _{JCP}	TCK clock period	100		ns			
t _{JCH}	TCK clock high time	50		ns			
t _{JCL}	TCK clock low time	50		ns			
t _{JPSU}	JTAG port setup time	20		ns			
t_{JPH}	JTAG port hold time	45		ns			
t _{JPCO}	JTAG port clock to output		25	ns			
t _{JPZX}	JTAG port high impedance to valid output		25	ns			
t _{JPXZ}	JTAG port valid output to high impedance		25	ns			
t _{JSSU}	Capture register setup time	20		ns			
t _{JSH}	Capture register hold time	45		ns			
t _{JSCO}	Update register clock to output		35	ns			
t _{JSZX}	Update register high impedance to valid output		35	ns			
t _{JSXZ}	Update register valid output to high impedance		35	ns			



For more information, see the following documents:

- Application Note 39 (IEEE Std. 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices)
- Jam Programming & Test Language Specification

Generic Testing

Each APEX 20K device is functionally tested. Complete testing of each configurable static random access memory (SRAM) bit and all logic functionality ensures 100% yield. AC test measurements for APEX 20K devices are made under conditions equivalent to those shown in Figure 32. Multiple test patterns can be used to configure devices during all stages of the production flow.

		Pevice Recommended Operating Condition	`	, B#	
Symbol	Parameter	Conditions	Min	Max	Unit
V _{CCINT}	Supply voltage for internal logic and input buffers	(4), (5)	2.375 (2.375)	2.625 (2.625)	V
V _{CCIO}	Supply voltage for output buffers, 3.3-V operation	(4), (5)	3.00 (3.00)	3.60 (3.60)	٧
	Supply voltage for output buffers, 2.5-V operation	(4), (5)	2.375 (2.375)	2.625 (2.625)	V
V _I	Input voltage	(3), (6)	-0.5	5.75	V
Vo	Output voltage		0	V _{CCIO}	V
T _J	Junction temperature	For commercial use	0	85	°C
		For industrial use	-40	100	°C
t _R	Input rise time			40	ns
t _F	Input fall time			40	ns

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{IH}	High-level input voltage		1.7, 0.5 × V _{CCIO} (9)		5.75	V
V _{IL}	Low-level input voltage		-0.5		0.8, 0.3 × V _{CCIO} (9)	٧
V _{OH}	3.3-V high-level TTL output voltage	I _{OH} = -8 mA DC, V _{CCIO} = 3.00 V (10)	2.4			٧
	3.3-V high-level CMOS output voltage	I _{OH} = -0.1 mA DC, V _{CCIO} = 3.00 V (10)	V _{CCIO} - 0.2			٧
	3.3-V high-level PCI output voltage	$I_{OH} = -0.5 \text{ mA DC},$ $V_{CCIO} = 3.00 \text{ to } 3.60 \text{ V}$ (10)	0.9 × V _{CCIO}			V
	2.5-V high-level output voltage	I _{OH} = -0.1 mA DC, V _{CCIO} = 2.30 V (10)	2.1			٧
		I _{OH} = -1 mA DC, V _{CCIO} = 2.30 V (10)	2.0			٧
		I _{OH} = -2 mA DC, V _{CCIO} = 2.30 V (10)	1.7			٧

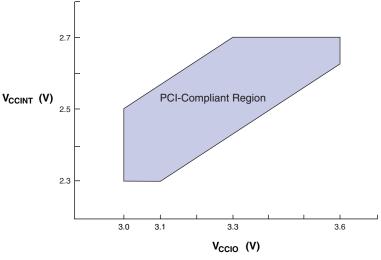


Figure 33. Relationship between V_{CCIO} & V_{CCINT} for 3.3-V PCI Compliance

Figure 34 shows the typical output drive characteristics of APEX 20K devices with 3.3-V and 2.5-V $V_{\rm CCIO}$. The output driver is compatible with the 3.3-V *PCI Local Bus Specification, Revision 2.2* (when VCCIO pins are connected to 3.3 V). 5-V tolerant APEX 20K devices in the -1 speed grade are 5-V PCI compliant over all operating conditions.

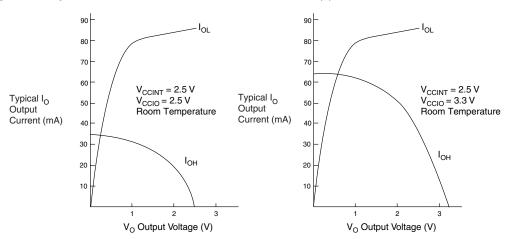


Figure 34. Output Drive Characteristics of APEX 20K Device Note (1)

Note to Figure 34:

(1) These are transient (AC) currents.

Table 31. APEX 2	Table 31. APEX 20K f _{MAX} Timing Parameters (Part 2 of 2)					
Symbol	Parameter					
t _{ESBDATACO2}	ESB clock-to-output delay without output registers					
t _{ESBDD}	ESB data-in to data-out delay for RAM mode					
t _{PD}	ESB macrocell input to non-registered output	-				
t _{PTERMSU}	ESB macrocell register setup time before clock					
t _{PTERMCO}	ESB macrocell register clock-to-output delay					
t _{F1-4}	Fanout delay using local interconnect					
t _{F5-20}	Fanout delay using MegaLab Interconnect					
t _{F20+}	Fanout delay using FastTrack Interconnect					
t _{CH}	Minimum clock high time from clock pin					
t _{CL}	Minimum clock low time from clock pin					
t _{CLRP}	LE clear pulse width					
t _{PREP}	LE preset pulse width					
t _{ESBCH}	Clock high time					
t _{ESBCL}	Clock low time					
t _{ESBWP}	Write pulse width					
t _{ESBRP}	Read pulse width					

Tables 32 and 33 describe APEX 20K external timing parameters.

Table 32. APEX 20K External Timing Parameters Note (1)				
Symbol	Clock Parameter			
t _{INSU}	Setup time with global clock at IOE register			
t _{INH}	Hold time with global clock at IOE register			
tоитсо	Clock-to-output delay with global clock at IOE register			

Table 33. APEX 20K External Bidirectional Timing Parameters Note (1)					
Symbol	Parameter	Conditions			
t _{INSUBIDIR}	Setup time for bidirectional pins with global clock at same-row or same-column LE register				
t _{INHBIDIR}	Hold time for bidirectional pins with global clock at same-row or same-column LE register				
^t OUTCOBIDIR	Clock-to-output delay for bidirectional pins with global clock at IOE register	C1 = 10 pF			
t _{XZBIDIR}	Synchronous IOE output buffer disable delay	C1 = 10 pF			
t _{ZXBIDIR}	Synchronous IOE output buffer enable delay, slow slew rate = off	C1 = 10 pF			

Table 110. Selectable I/O Standard Output Delays								
Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit	
	Min	Max	Min	Max	Min	Max	Min	
LVCMOS		0.00		0.00		0.00	ns	
LVTTL		0.00		0.00		0.00	ns	
2.5 V		0.00		0.09		0.10	ns	
1.8 V		2.49		2.98		3.03	ns	
PCI		-0.03		0.17		0.16	ns	
GTL+		0.75		0.75		0.76	ns	
SSTL-3 Class I		1.39		1.51		1.50	ns	
SSTL-3 Class II		1.11		1.23		1.23	ns	
SSTL-2 Class I		1.35		1.48		1.47	ns	
SSTL-2 Class II		1.00		1.12		1.12	ns	
LVDS		-0.48		-0.48		-0.48	ns	
CTT		0.00		0.00		0.00	ns	
AGP		0.00		0.00		0.00	ns	

Power Consumption

To estimate device power consumption, use the interactive power calculator on the Altera web site at http://www.altera.com.

Configuration & Operation

The APEX 20K architecture supports several configuration schemes. This section summarizes the device operating modes and available device configuration schemes.

Operating Modes

The APEX architecture uses SRAM configuration elements that require configuration data to be loaded each time the circuit powers up. The process of physically loading the SRAM data into the device is called configuration. During initialization, which occurs immediately after configuration, the device resets registers, enables I/O pins, and begins to operate as a logic device. The I/O pins are tri-stated during power-up, and before and during configuration. Together, the configuration and initialization processes are called *command mode*; normal device operation is called *user mode*.

Before and during device configuration, all I/O pins are pulled to $V_{\mbox{\scriptsize CCIO}}$ by a built-in weak pull-up resistor.

Version 4.1

APEX 20K Programmable Logic Device Family Data Sheet version 4.1 contains the following changes:

- t_{ESBWEH} added to Figure 37 and Tables 35, 50, 56, 62, 68, 74, 86, 92, 97, and 104.
- Updated EP20K300E device internal and external timing numbers in Tables 79 through 84.